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Mobile Intel® CM236 Chipset (Intel® GL82CM236 PCH)

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Specifications

Essentials	
Status	Launched
Launch Date	Q3'15
DMI3	8 GT/s
Embedded Options Available	Yes
Lithography	22 nm
TDP	3.67 W
Recommended Customer Price	
Datasheet	Link
Supports Overclocking	Yes

Memory Specifications	
# of DIMMs per channel	2

Graphics Specifications	
Intel® Clear Video Technology	Yes
# of Displays Supported ‡	3

Expansion Options	
PCI Support	No
PCI Express Revision	3.0
PCI Express Configurations ‡	x1, x2, x4
Max # of PCI Express Lanes	20

I/O Specifications	
USB Revision	3.0/2.0
# of USB Ports	14
USB 3.0	Up to 10
USB 2.0	Up to 14
Max # of SATA 6.0 Gb/s Ports	8
RAID Configuration	0/1/5/10
Integrated LAN	Integrated MAC

Package Specifications	
Package Size	23mm x 23mm
Low Halogen Options Available	See MDDS

Advanced Technologies	
Intel® Virtualization Technology for Directed I/O (VT-q) ‡	Yes
Intel® vPro Technology ‡	Yes
Intel® ME Firmware Version	11.0
Intel® HD Audio Technology	Yes
Intel® Rapid Storage Technology	Yes
Intel® Rapid Storage Technology enterprise	Yes
Intel® Smart Response Technology	Yes
Intel® Stable Image Platform Program (SIPP)	Yes
Intel® Small Business Advantage	Yes

Intel® Platform Protection Technology	
Trusted Execution Technology ‡	Yes

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PCN/MDDS Information

SR2CE
943519: MDDS

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warrant, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit <http://www.intel.com/content/www/us/en/gaming/overclocking/overclocking-intel-processors.html>

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